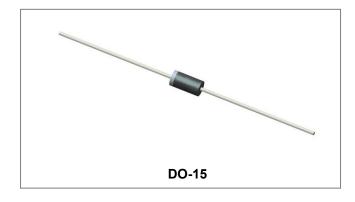


**RL306G** 



# **RL306G GENERAL PURPOSE PLASTIC RECTIFIER**



# **Circuit Diagram**

# Cathode Anode

#### Features

- Low forward voltage drop
- Low leakage current
- High forward surge capability
- Solder Resistance 270℃ / 7s, or 380℃ / 3s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

#### **Mechanical Data**

- Case: Molded plastic, DO-15
- Terminals: Axial leads, solderable per MIL-STD-750, method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any

#### **Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	-	600	V
RMS Voltage	V <sub>RMS</sub>	-	420	V
DC Blocking Voltage	V <sub>DC</sub>	-	600	V
Average Forward Current(Per Device)	I <sub>F (AV)</sub>	50% duty cycle @T <sub>A</sub> =75℃ rectangular wave form	3	A
I <sup>2</sup> t Rating for fusing (t < 8.3ms)	l²t	-	60	A²S
Peak One Cycle Non-Repetitive Surge Current (Per Leg)	I <sub>FSM</sub>	8.3 ms, half Sine pulse	120	A

#### **Electrical Characteristics:**

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop(Per Leg)*	V <sub>F1</sub>	@ 3A, Pulse, TJ = 25℃	1.0	1.1	V
Reverse Current(Per Leg)*	I <sub>R1</sub>	@V <sub>R</sub> = rated V <sub>R</sub> T <sub>J</sub> = 25℃	0.02	5	μA
	I <sub>R2</sub>	@V <sub>R</sub> = rated V <sub>R</sub> T <sub>J</sub> = 125℃	10	100	μA
Junction Capacitance(Per Leg)	CJ	@V <sub>R</sub> = 4V, T <sub>C</sub> = 25 °C f <sub>SIG</sub> = 1MHz	45	-	pF

\* Pulse width < 300  $\mu$ s, duty cycle < 2%

• China - Germany - Korea - Singapore - United States •

http://www.smc-diodes.com - sales@ smc-diodes.com -



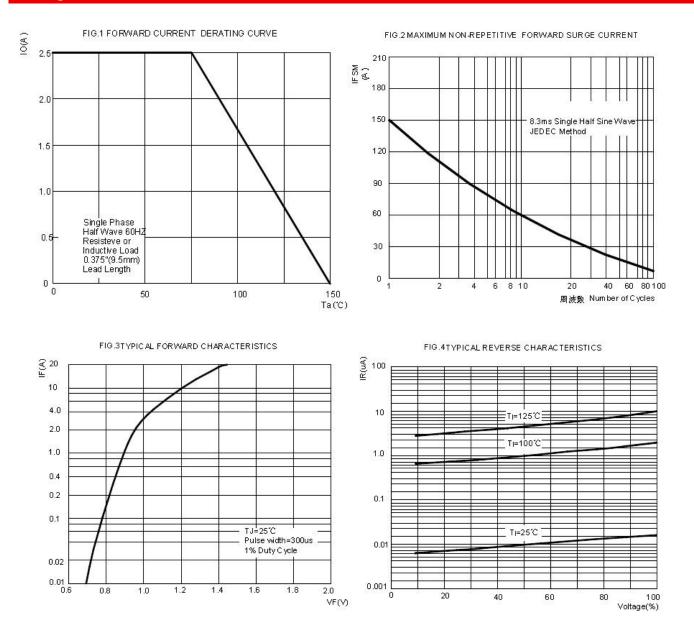
# **RL306G**

RoHS 🗭

# **Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Maximum Thermal Resistance Junction to Ambient	$R_{ heta JA}$	DC operation	45	°C/W
Case Style	DO-15			

## **Ratings and Characteristics Curves**

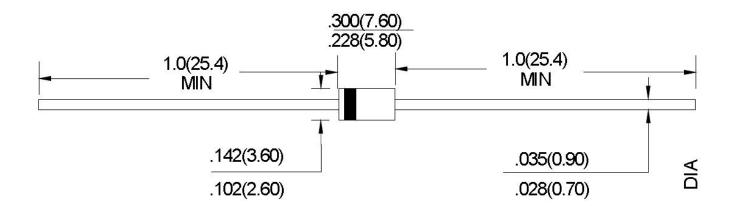




**RL306G** 

RoHS 🗭

## Mechanical Dimensions DO-15 (Inches/Millimeters)

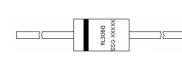


#### **Ordering Information**

Device	Package	Shipping	
RL306G	DO-15 (Pb-Free)	3000pcs /tape	

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

# Marking Diagram



#### Where XXXXX is YYWWL

RL306G	= Part Name
VV	= Year

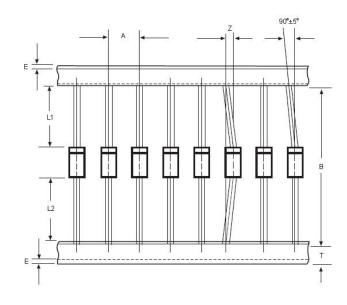
=	Year
_	Woold

YY WW L

-	vvee	7K
=	Lot I	Number

Cautions: Molding resin Epoxy resin UL:94V-0

## **Carrier Tape Specification DO-15**



SYMBOL	Millimeters		
	Min.	Max.	
А	4.50	5.50	
В	50.9	53.9	
Z	-	1.20	
Т	5.60	6.40	
E	-	0.80	
IL1-L2I	-	1.0	



#### Technical Data Data Sheet N1928, Rev. -





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